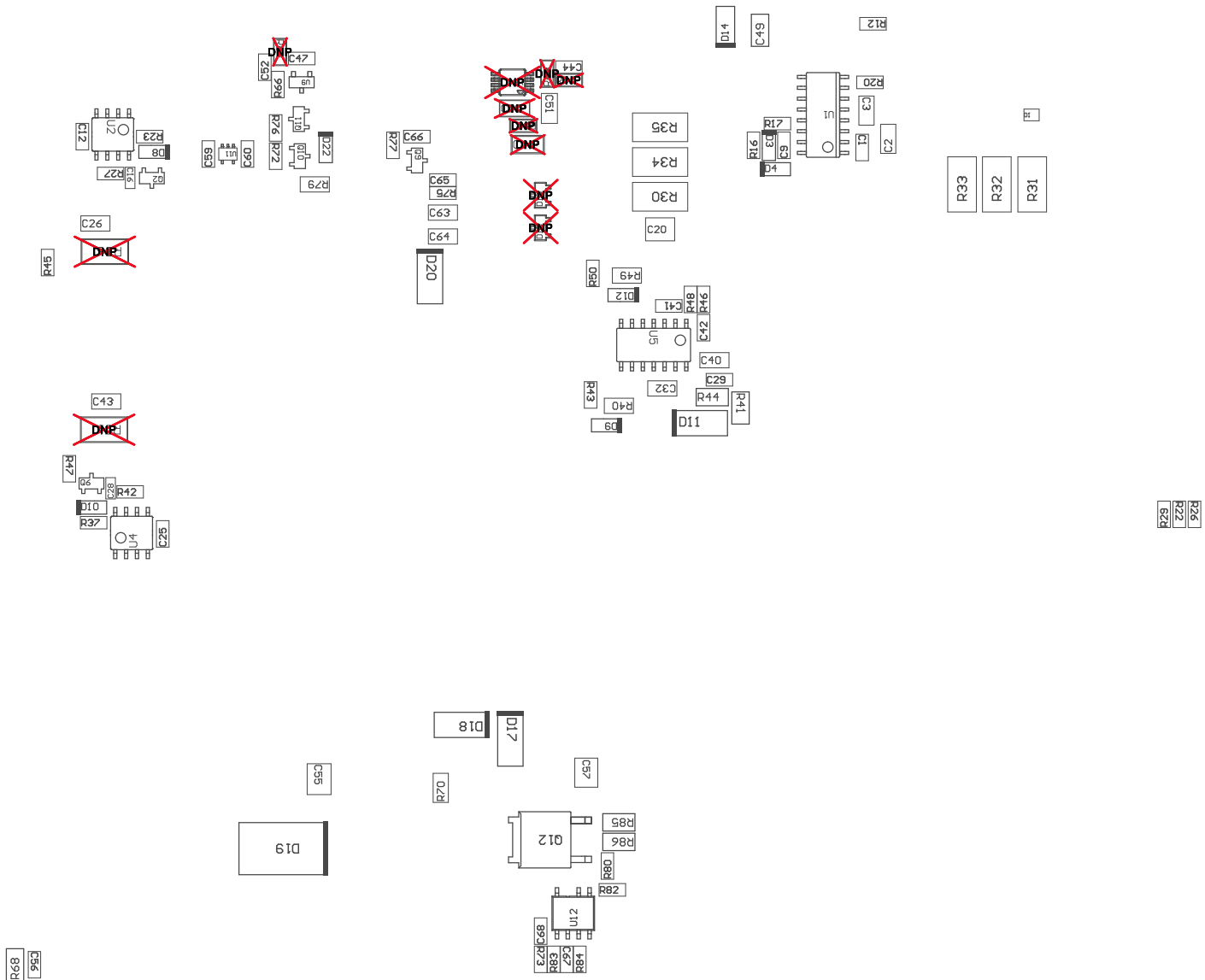


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
	TID #:		
PLOT NAME = Top Assembly Drawing	GENERATED : 9/16/2015 8:19:05 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
	TID #:		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/16/2015	8:19:06 AM	TEXAS INSTRUMENTS

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